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Surface Mount 3000 Watt Transient Voltage Suppressor

Screening in reference to MIL-PRF-19500 available

DESCRIPTION

The MSMLG(J)5.0A through MXLSMLG(J)170A series of high-reliability Transient Voltage Suppressors (TVSs) protect circuits from voltage spikes containing up to 3000 W (10/1000 μs model pulse. The SMLG gull-wing design in the DO-215AB package allows for visible solder connections. The SMLJ J-bend design in the DO-214AB package allows for greater PC board mounting density. Selections include unidirectional and bidirectional as well as RoHS compliant versions. These are available with a variety of upscreening options for enhanced reliability. They protect against the secondary effects of lightning per IEC61000-4-5 and against voltage pulses from inductive switching environments and induced by RF radiation. Since their response time is virtually instantaneous, they can also be used in protection from ESD and EFT per IEC61000-4-2 and IEC61000-4-4.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

- High reliability devices with fabrication and assembly lot traceability for all M prefix devices
- All devices are 100% surge tested
- 3σ lot norm screening performed on standby current (I_D) for all M prefix devices
- Available in both unidirectional and bidirectional versions
- Moisture classification is "Level 1" with no dry pack required per IPC/JEDEC J-STD-020B for all M prefix devices.
- Enhanced reliability screening options with M prefix are available in reference to MIL-PRF-19500. Refer to High Reliability Up-Screened Plastic Products Portfolio for more details on the screening options.

(See part nomenclature for all available options.)

- RoHS compliant versions available
- Axial-lead equivalent packages for thru-hole mounting are available as M5KP5.0A to M5KP110CA with 5000 W rating (contact Microsemi for other surface mount options).

APPLICATIONS / BENEFITS

- Suppresses transients up to 3000 watts (10/1000 us test pulse see Figure 2)
- Selections for 5.0 to 170 volts standoff voltages (V_{WM})
- Protection from switching transients and induced RF
- Protection from ESD, and EFT per IEC 61000-4-2 and IEC 61000-4-4
- Secondary lightning protection per IEC61000-4-5 with 42 ohms source impedance:

Class 1 & 2: SML 5.0A to SML 170A or CA

Class 3: SML 5.0A to SML 150A or CA

Class 4: SML 5.0A to SML 75A or CA

Secondary lightning protection per IEC61000-4-5 with 12 ohms source impedance:

Class 1: SML 5.0A to SML 170A or CA

Class 2: SML 5.0A to SML 90A or CA

Class 3: SML 5.0A to SML 48A or CA

Class 4: SML 5.0A to SML 24A or CA

Secondary lightning protection per IEC61000-4-5 with 2 ohms source impedance:

Class 2: SML 5.0A to SML 43A or CA

Class 3: SML 5.0A to SML 22A or CA

Class 4: SML 5.0A to SML10A or CA



DO-215AB Package



DO-214AB Package

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MAXIMUM RATINGS

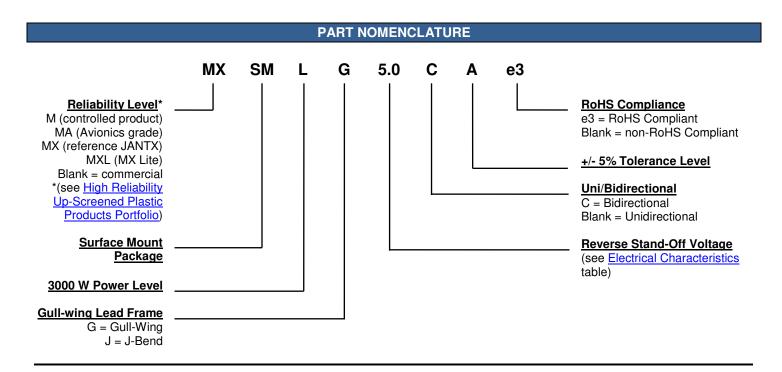
Parameters/Test Conditions	Symbol	Value	Unit	
Junction and Storage Temperature	T _J and T _{STG}	-65 to +150	ōC	
Thermal Resistance Junction-to-Lead	R _{OJL}	17.5	ºC/W	
Thermal Resistance Junction-to-Amb	ent (1)	$R_{\Theta JA}$	77.5	ºC/W
Peak Pulse Power Dissipation @ 25 9	P _{PP}	3000	W	
(at 10/1000 μs, see Figures 1, 2, and				
Impulse Repetition Rate (duty factor)	df	0.01 or less	%	
t _{clamping} (0 volts to V _(BR) min.) Unidirectional		t _{clamping}	<100	ps
	Bidirectional		<5	ns
Rated Average Power Dissipation T _L = +45 °C		P _{M(AV)}	6	W
		1.61 ⁽¹⁾		
Maximum Forward Surge Current (2)	I _{FSM}	200	A (pk)	
Solder Temperature @ 10 s	T _{SP}	260	°C	

Notes: 1. When mounted on FR4 PC board (1oz Cu) with recommended footprint (see last page)

2. Peak impulse of 8.3 ms half-sine wave at 25 °C (unidirectional only)

MECHANICAL and PACKAGING

- CASE: Void-free transfer molded thermosetting epoxy body meeting UL94V-0
- TERMINALS: Tin-lead or RoHS compliant annealed matte-tin plating. Solderable to MIL-STD-750, method 2026.
- MARKING: Part number marked on package
- POLARITY: Cathode indicated by band. No cathode band on bi-directional devices
- TAPE & REEL option: Standard per EIA-481-B with 16 mm tape (add "TR" suffix to part number). Consult factory for quantities.
- WEIGHT: Approximately 0.25 grams
- See Package Dimensions on last page.





	SYMBOLS & DEFINITIONS				
Symbol	Definition				
I _(BR)	Breakdown Current: The current used for measuring breakdown voltage V _(BR) .				
I _D	Standby Current: The current at the rated standoff voltage (V _{WM}).				
I _F	Forward Current: The forward current dc value, no alternating component.				
Io	Average Rectified Output Current: The output current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.				
I _{PP}	Peak Impulse Current: The peak current during the impulse.				
P _{PP}	Peak Pulse Power: The peak power dissipation resulting from the peak impulse current I _{PP} .				
Vc	Clamping Voltage: Maximum clamping voltage at specified IPP (Peak Pulse Current) at the specified pulse conditions.				
$V_{(BR)}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.				
V _{WM}	Working Peak Voltage: The maximum peak voltage that can be applied over the operating temperature range. This is also referred to as standoff voltage.				

ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise stated

PART N	UMBER	REVERSE STAND-OFF VOLTAGE V _{WM}	BREAKDOV VOLTAGI V _(BR) @ I _{(E} Volts	E	MAXIMUM CLAMPING VOLTAGE @ I _{PP}	PEAK PULSE CURRENT (See <u>Fig. 2</u>) I _{PP}	MAXIMUM STANDBY CURRENT @ V _{WM}
Cull Win n	J-Bend	Valta	MIN. MAX.	I _(BR)	Valta	A	I _D
Gull-Wing SMLG5.0A	SMLJ5.0A	Volts 5.0	6.40 – 7.00	mA	Volts 9.2	Amps 326.0	μ Α 1000
					9.2 10.3	326.0 291.3	
SMLG6.0A	SMLJ6.0A	6.0	6.67 – 7.37	10			1000 500
SMLG6.5A SMLG7.0A	SMLJ6.5A SMLJ7.0A	6.5 7.0	7.22 – 7.98 7.78 – 8.60	10 10	11.2 12.0	267.9 250.0	200
SMLG7.5A	SMLJ7.5A	7.5	8.33 – 9.21	10	12.9	232.6	100
SMLG8.0A	SMLJ8.0A	8.0	8.89 – 9.83		13.6	220.6	50
SMLG8.5A	SMLJ8.5A	8.5	9.44 – 10.4	1	14.4	208.4	25
SMLG9.0A	SMLJ9.0A	9.0	9.44 = 10.4 10.0 = 11.1		15.4	194.8	10
SMLG10A	SMLJ10A	10	11.1 – 12.3	1	17.0	176.4	5
SMLG11A	SMLJ11A	11	12.2 – 13.5		18.2	164.8	5
SMLG11A SMLG12A	SMLJ12A	12	13.3 – 14.7	1	19.9	150.6	5
SMLG13A	SMLJ12A SMLJ13A	13	14.4 – 15.9		21.5	139.4	5
SMLG13A SMLG14A	SMLJ14A	14	15.6 – 17.2	1	23.2	129.4	2
SMLG14A SMLG15A	SMLJ15A	15	16.7 – 18.5	li	24.4	123.0	2
SMLG16A	SMLJ16A	16	17.8 – 19.7	1	26.0	115.4	2
SMLG17A	SMLJ17A	17	18.9 – 20.9		27.6	106.6	2
SMLG18A	SMLJ18A	18	20.0 – 22.1	1	29.2	102.8	2
SMLG20A	SMLJ20A	20	22.2 – 24.5	Ιί	32.4	92.6	2
SMLG22A	SMLJ22A	22	24.4 – 26.9	1	35.5	84.4	2
SMLG24A	SMLJ24A	24	26.7 – 29.5	li	38.9	77.2	2
SMLG26A	SMLJ26A	26	28.9 – 31.9	1	42.1	71.2	2
SMLG28A	SMLJ28A	28	31.1 – 34.4	1	45.4	66.0	2
SMLG30A	SMLJ30A	30	33.3 – 36.8	1	48.4	62.0	2
SMLG33A	SMLJ33A	33	36.7 – 40.6	1	53.3	56.2	2
SMLG36A	SMLJ36A	36	40.0 – 44.2	1	58.1	51.6	2
SMLG40A	SMLJ40A	40	44.4 – 49.1	1	64.5	46.4	2
SMLG43A	SMLJ43A	43	47.8 – 52.8	1	69.4	43.2	2
SMLG45A	SMLJ45A	45	50.0 - 55.3	1	72.7	41.2	2
SMLG48A	SMLJ48A	48	53.3 - 58.9	1	77.4	38.8	2
SMLG51A	SMLJ51A	51	56.7 - 62.7	1	82.4	36.4	2
SMLG54A	SMLJ54A	54	60.0 - 66.3	1	87.1	34.4	2
SMLG58A	SMLJ58A	58	64.4 – 71.2	1	93.6	32.0	2
SMLG60A	SMLJ60A	60	66.7 – 73.7	1	96.8	31.0	2
SMLG64A	SMLJ64A	64	71.1 – 78.6	1	103.0	29.2	2
SMLG70A	SMLJ70A	70	77.8 – 86.0	1	113	26.6	2
SMLG75A	SMLJ75A	75	83.3 – 92.1	1	121	24.8	2

Continued.



ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise stated (continued)

MICROSEMI P	ART NUMBER	REVERSE STAND-OFF VOLTAGE V _{WM}	BREAKDO\ VOLTAGI V _(BR) @ I _{(E} Volts	E	MAXIMUM CLAMPING VOLTAGE @ I _{PP}	PEAK PULSE CURRENT (See Fig. 2) I _{PP}	MAXIMUM STANDBY CURRENT @ V _{WM}
Gull-Wing	J-Bend	Volts	MIN. MAX.	I _(BR) mA	Volts	Amps	Ι _D μ A
SMLG78A	SMLJ78A	78	86.7 – 95.8	1	126	22.8	2
SMLG85A	SMLJ85A	85	94.4 - 104.0	1	137	20.8	2
SMLG90A	SMLJ90A	90	100 – 111	1	146	20.6	2
SMLG100A	SMLJ100A	100	111 – 123	1	162	18.6	2
SMLG110A	SMLJ110A	110	122 – 135	1	177	16.8	2
SMLG120A	SMLJ120A	120	133 – 147	1	193	15.6	2
SMLG130A	SMLJ130A	130	144 – 159	1	209	14.4	2
SMLG150A	SMLJ150A	150	167 – 185	1	243	12.4	2
SMLG160A	SMLJ160A	160	178 – 197	1	259	11.6	2
SMLG170A	SMLJ170A	170	189 – 209	1	275	11.0	2

NOTE 1: Bidirectional capacitance is half that shown in figure 4 at zero volts.



GRAPHS

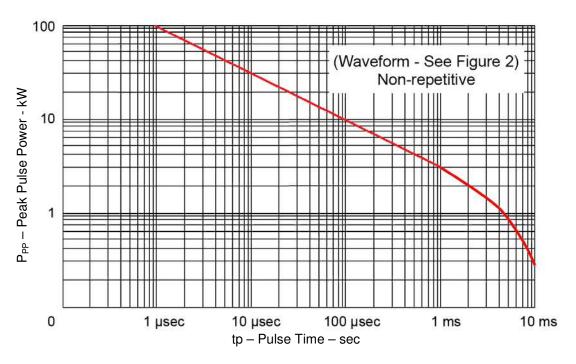


FIGURE 1
Peak Pulse Power vs. Pulse Time

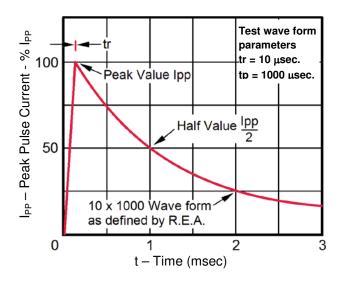
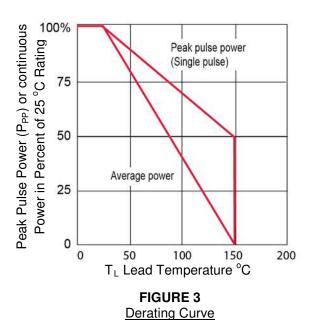
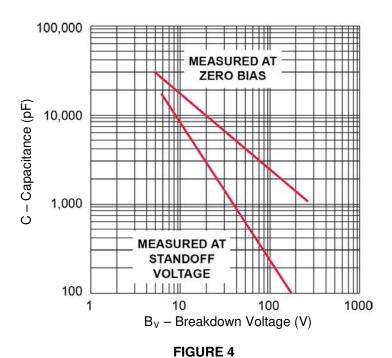


FIGURE 2
Pulse Waveform



GRAPHS (continued)





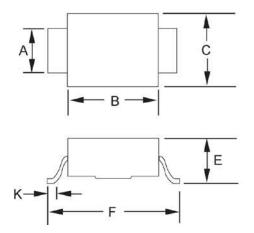
Typical Capacitance vs.

Breakdown Voltage (unidirectional configuration)

NOTE: Bidirectional capacitance is half that shown at zero volts.



PACKAGE DIMENSIONS

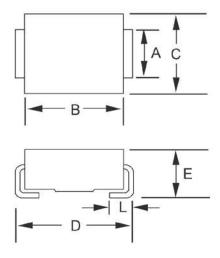


SMLG (DO-215AB)

	Dimensions				
Ltr	Inch		Millin	neters	
	Min	Max	Min	Max	
Α	0.115	0.121	2.92	3.07	
В	0.260	0.280	6.60	7.11	
С	0.220	0.245	5.59	6.22	
E	0.077	0.110	1.95	2.80	
F	0.380	0.400	9.65	10.16	
K	0.025	0.040	0.635	1.016	

NOTES: Dimension "E" exceeds the JEDEC outline as shown.

Typical Standoff Height: 0.004" – 0.008" (0.1 mm – 0.2 mm).



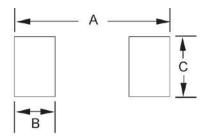
SMLJ (DO-214AB)

	Dimensions						
Ltr	Inch		Millin	neters			
	Min	Min Max		Max			
Α	0.115	0.121	2.92	3.07			
В	0.260	0.280	6.60	7.11			
C	0.220	0.245	5.59	6.22			
D	0.305	0.320	7.75	8.13			
Е	0.077	0.110	1.95	2.80			
L	0.030	0.060	0.760	1.52			

NOTES: Dimension "E" exceeds the JEDEC outline in height as shown. Typical Standoff Height: 0.004" – 0.008" (0.1~mm – 0.2~mm).



PAD LAYOUT



	SMLG (DO-215AB)				
Ltr	Ltr Inch Millimeters				
Α	0.510	12.95			
В	0.110	2.79			
С	0.150	3.81			

	SMLJ (DO-214AB)			
Ltr Inch Millimeters				
Α	0.390	9.90		
В	0.110	2.79		
С	0.150	3.81		